Amendments to the Claims:

1-13. (Cancelled)

14. (Currently Amended) A semi-conductor package comprising:

a top layer having a die mounted thereon, said die having a corner; and

a plurality of layers under the top layer, said plurality of layers comprising a bottom routing layer having signal traces thereon, and a ball pad layer under the bottom routing layer, said ball pad layer having a plurality of ball pads, wherein none of the signal traces of the bottom routing layer are located ~~under~~ over ball pads of the ball pad layer which are disposed in an area within two ball pad pitches of the corner of the die.

15. (Previously Presented) A package as recited in claim 14, wherein none of the signal traces of the bottom routing layer are located within two ball pad pitches of the corner of the die.

16. (Previously Presented) A package as recited in claim 14, wherein said ball pad layer has a plurality of ball pads dispersed thereon and no metal traces on the ball pad layer which are connected to the ball pads.

17. (Previously Presented) A package as recited in claim 14, wherein the package comprises nine layers with the routing layer being the eighth layer and the ball pad layer being the ninth layer, on a bottom of the package.

18. (Previously Presented) A package as recited in claim 14, wherein the die is mounted to the top layer in an arrangement other than a pin connection.

19. (Previously Presented) A package as recited in claim 14, wherein the signal traces on the bottom routing layer comprise at least one voltage bus bar.

20. (Currently Amended) A semi-conductor package comprising:

a top layer having a die mounted thereon, said die having a corner defining a surrounding area of increased stress; and

a plurality of layers under the top layer, said plurality of layers comprising a bottom routing layer having signal traces thereon, and a ball pad layer under the bottom routing layer, said ball pad layer having a plurality of ball pads dispersed thereon, wherein none of the signal traces of the bottom routing layer are located ~~with~~ within the area of increased stress defined by the corner of the die.

21. (Previously Presented) A package as recited in claim 20, wherein none of the signal traces of the bottom routing layer are located within two ball pad pitches of the corner of the die.

22. (Previously Presented) A package as recited in claim 20, wherein said ball pad layer has a plurality of ball pads dispersed thereon and no metal traces on the ball pad layer which are connected to the ball pads.

23. (Previously Presented) A package as recited in claim 20, wherein the package comprises nine layers with the routing layer being the eighth layer and the ball pad layer being the ninth layer, on a bottom of the package.

24. (Previously Presented) A package as recited in claim 20, wherein the die is mounted to the top layer in an arrangement other than a pin connection.

25. (Previously Presented) A package as recited in claim 20, wherein the signal traces on the bottom routing layer comprise at least one voltage bus bar.